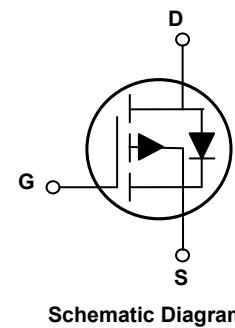
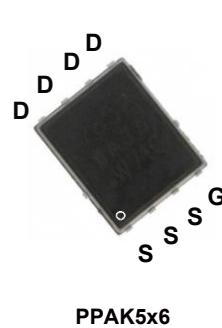


### Main Product Characteristics

BV <sub>DSS</sub>	-60V
R <sub>DS(ON)</sub>	47mΩ
I <sub>D</sub>	-25A



### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFP0625 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

### Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V <sub>DS</sub>	-60	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous (T <sub>C</sub> =25°C)	I <sub>D</sub>	-25	A
Drain Current-Continuous (T <sub>C</sub> =100°C)		-16	A
Drain Current-Pulsed <sup>1</sup>	I <sub>DM</sub>	-100	A
Single Pulse Avalanche Energy <sup>2</sup>	E <sub>AS</sub>	58	mJ
Single Pulse Avalanche Current <sup>2</sup>	I <sub>AS</sub>	-34	A
Power Dissipation (T <sub>C</sub> =25°C)	P <sub>D</sub>	72	W
Power Dissipation-Derate Above 25°C		0.578	W/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	62	°C/W
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	1.73	°C/W
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C
Operating Junction Temperature Range	T <sub>J</sub>	-55 to +150	°C

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-60	-	-	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=-60\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	-1	$\mu\text{A}$
		$V_{\text{DS}}=-48\text{V}, V_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$	-	-	-10	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics</b>						
Static Drain-Source On - Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-8\text{A}$	-	41	47	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-6\text{A}$	-	53	64	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.2	-1.6	-2.5	V
Forward Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=-10\text{V}, I_{\text{S}}=-3\text{A}$	-	11	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>2,3</sup>	$Q_g$	$V_{\text{DS}}=-30\text{V}, I_{\text{D}}=-10\text{A}, V_{\text{GS}}=-10\text{V}$	-	19	30	nC
Gate-Source Charge <sup>2,3</sup>	$Q_{\text{gs}}$		-	2.5	3.8	
Gate-Drain Charge <sup>2,3</sup>	$Q_{\text{gd}}$		-	4.3	6.5	
Turn-On Delay Time <sup>2,3</sup>	$T_{\text{d(on)}}$	$V_{\text{DD}}=-30\text{V}, R_{\text{G}}=25\Omega, V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-10\text{A}$	-	25	40	nS
Rise Time <sup>2,3</sup>	$T_r$		-	58	95	
Turn-Off Delay Time <sup>2,3</sup>	$T_{\text{d(off)}}$		-	65	110	
Fall Time <sup>2,3</sup>	$T_f$		-	35	55	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	1200	1800	pF
Output Capacitance	$C_{\text{oss}}$		-	85	130	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	60	90	
Gate Resistance	$R_g$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, F=1\text{MHz}$	-	14	-	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_s$	Force Current	-	-	-25	A
Pulsed Source Current	$I_{\text{SM}}$		-	-	-50	A
Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-1\text{A}, T_J=25^\circ\text{C}$	-	-	-1	V
Reverse Recovery Time	$T_{\text{rr}}$	$V_R=-50\text{V}, I_{\text{S}}=-10\text{A}, \frac{di}{dt}=100\text{A}/\mu\text{s}, T_J=25^\circ\text{C}$	-	30	-	nS
Reverse Recovery Charge	$Q_{\text{rr}}$		-	20	-	nC

Note:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=-25\text{V}, V_{\text{GS}}=-10\text{V}, L=0.1\text{mH}, I_{\text{AS}}=-34\text{A}$ , starting  $T_J=25^\circ\text{C}$ .
3. Pulse test: pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

## Typical Electrical and Thermal Characteristic Curves

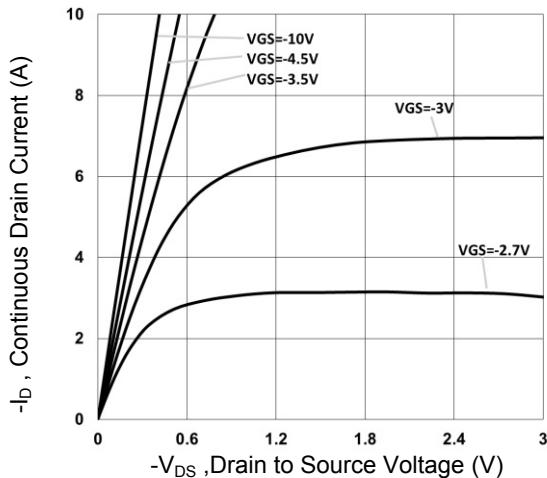


Fig.1 Typical Output Characteristics

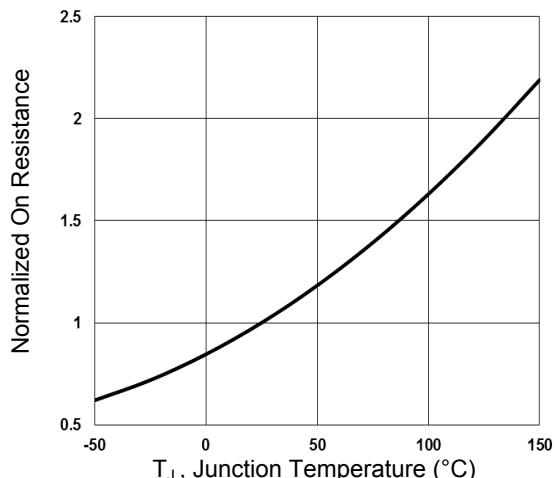


Fig.2 Normalized  $R_{DS(ON)}$  vs.  $T_J$

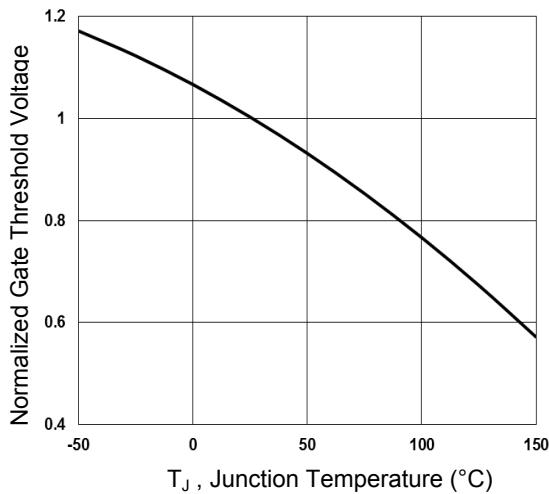


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

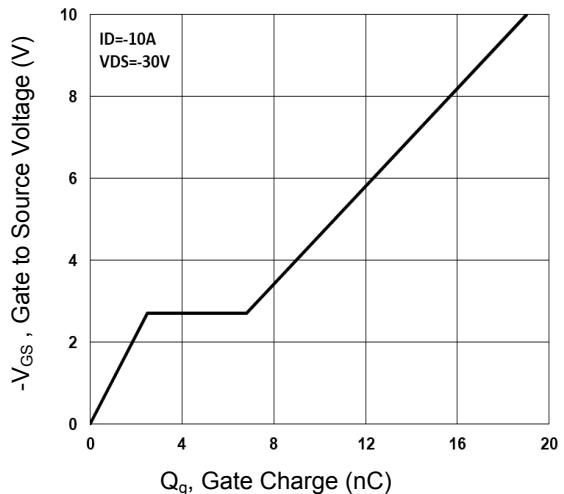


Fig.4 Gate Charge Waveform

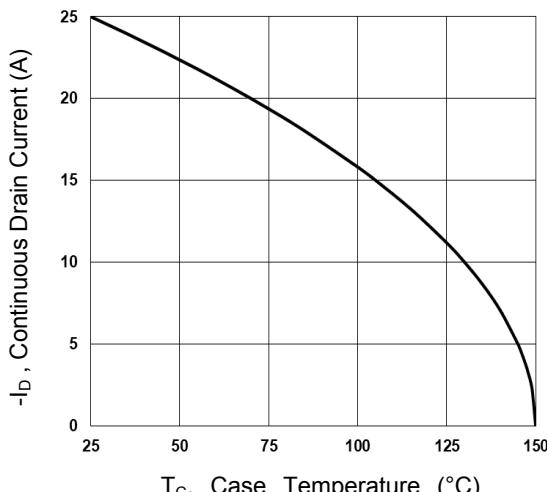


Fig.5 Continuous Drain Current vs.  $T_c$

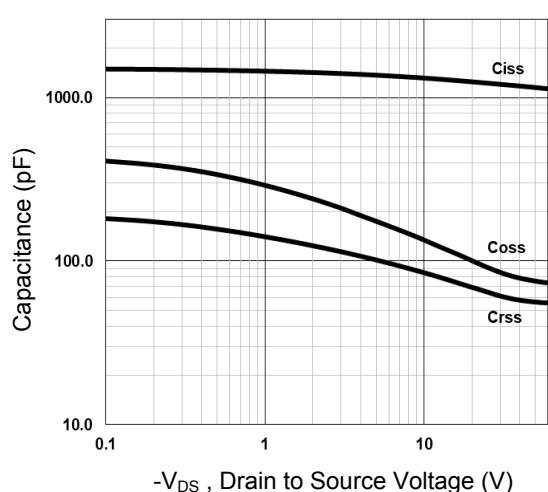


Fig.6 Capacitance Characteristics

## Typical Electrical and Thermal Characteristic Curves

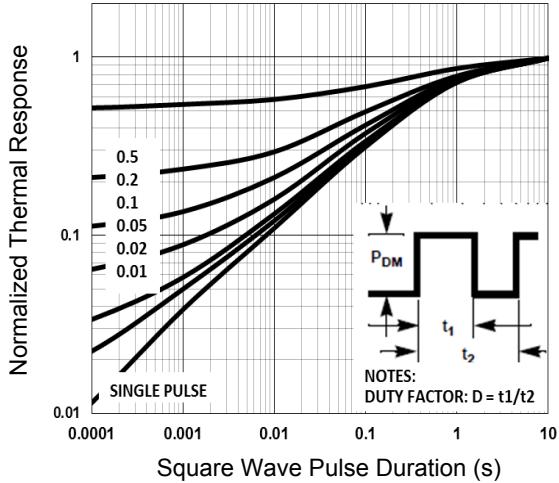


Fig.7 Normalized Transient Impedance

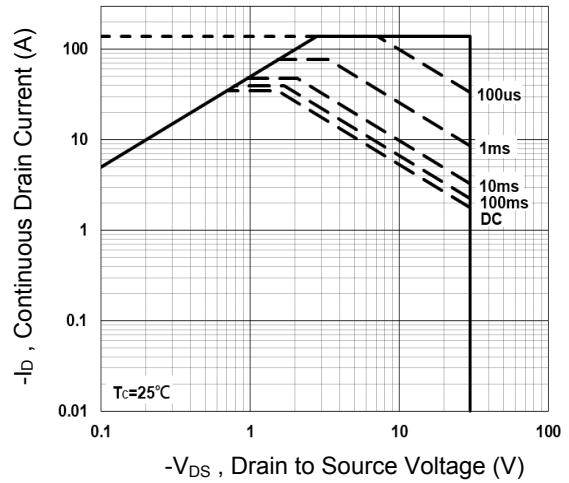
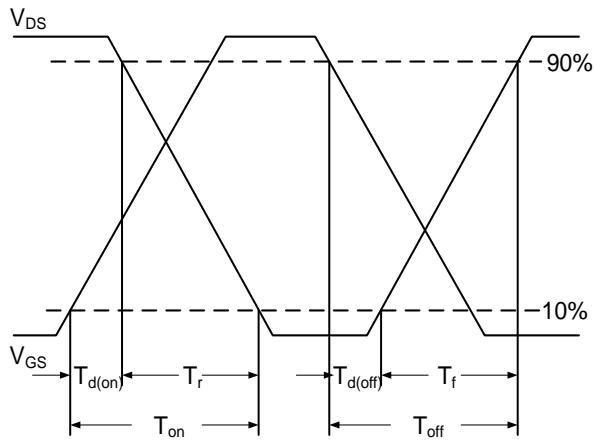


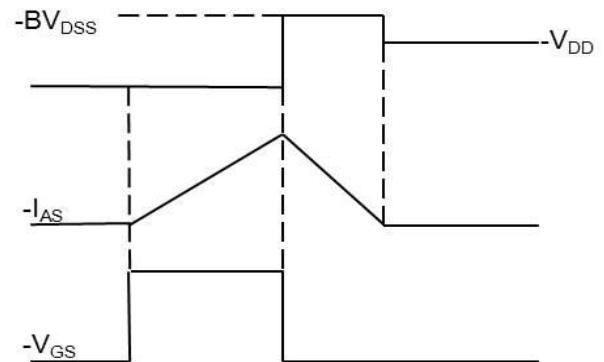
Fig.8 Maximum Safe Operation Area

## Typical Electrical and Thermal Characteristic Curves



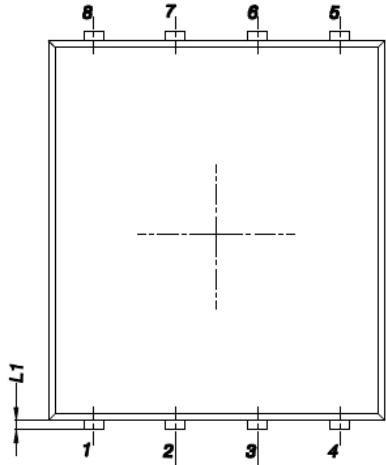
**Fig.9** Switching Time Waveform

$$EAS = \frac{1}{2} L \times (-I_{AS})^2 \times \frac{-BV_{DSS}}{-BV_{DSS} - (-V_{DD})}$$

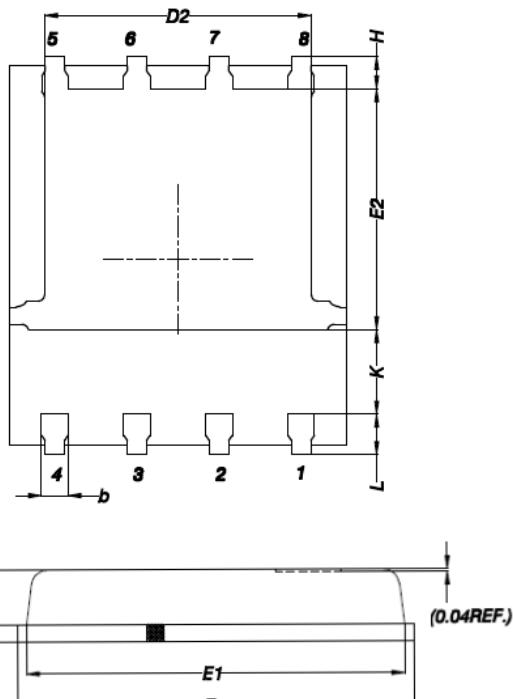


**Fig.10** EAS Waveform

### Package Outline Dimensions



### PPAK5x6



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.200	0.850	0.047	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.400	4.800	0.212	0.189
D2	4.310	3.610	0.170	0.142
E	6.300	5.850	0.248	0.230
E1	5.960	5.450	0.235	0.215
E2	3.920	3.300	0.154	0.130
e	1.27BSC		0.05BSC	
H	0.650	0.380	0.026	0.015
K	---	1.100	---	0.043
L	0.710	0.380	0.028	0.015
L1	0.250	0.050	0.009	0.002
θ	12°	0°	12°	0°